

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Wireless MEMS Incorporated	07/19/2011
RECEIVING PARTY DATA	
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Property Type	Number
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Total Attachments: 1 source=WMI002-CIP - new#page1.tif	

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Invention Title: MICROELECTROMECHANICAL DEVICE HAVING A COMMON GROUND PLANE LAYER AND A SET OF CONTACT TEETH AND METHOD FOR MAKING THE SAME

ASSIGNMENT

WHEREAS, **Wireless MEMS Incorporated**, a corporation organized and existing under the laws of the State of Delaware, United States of America and having a place of business at 517 Hastings Court, Oak Park, California 91377, United States of America, (hereinafter "Assignor") is the sole owner of **MICROELECTROMECHANICAL DEVICE HAVING A COMMON GROUND PLANE LAYER AND A SET OF CONTACT TEETH AND METHOD FOR MAKING THE SAME** (hereinafter "Invention") for which a United States Patent issued on September 5, 2006, Patent Number 7,101,724.

AND

WHEREAS, **Chia-Shing Chou of 517 Hastings Court, Oak Park, California 91377 United States of America**, (hereinafter "Assignee"), is desirous of acquiring the entire right, title, and interest in the Invention within the United States of America and its territorial possessions, and in all foreign countries in which intellectual or industrial property protection may be granted therefor.


NOW, THEREFORE, for good and valuable consideration, the receipt whereof is hereby acknowledged, I, the Assignor desire to and do hereby assign, sell, and transfer unto Assignee the full and exclusive right to the Invention in the United States of America and its territorial possessions and in all foreign countries, as well as, the entire right, title and interest in and to any and all intellectual or industrial property rights including, but not limited to, Patents, designs, utility models, and inventor certificates, as well as continuations, divisional, and reissues which may be granted therefore in the United States of America and its territorial possessions and in all foreign countries, I hereby authorize and request the U.S. Patent Offices and the equivalent offices at foreign countries, to issue to the Assignee, any and all applicable intellectual or industrial property rights in the Invention, for the Assignee's sole use and benefit; and for the use and benefit of his legal representatives, to the full end of the term for which United States and foreign Patents or the like may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

I further covenant and agree with the Assignee that I have a full and unencumbered title to the invention hereby assigned, which title I warrant unto the Assignee, and I further agree that I will, without demanding any further consideration therefore, at the request and at the expense of the Assignee, do all lawful and just acts, including the execution and acknowledgment of instruments, that may be or become necessary for obtaining, sustaining, extending, reissuing or reexamining United States and foreign Patents or the like for the Invention, and for maintaining and perfecting the Assignee's right to the Invention and any and all intellectual or industrial property rights in it, particularly in cases of interference, conflict, opposition and litigation.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

Executed this 19th day of July, 2011,

at TAIPEI (city).


Signature of the Wireless MEMS Incorporated Authorized Signatory

CHIA-SHING CHOU, President
Name and title of the Wireless MEMS Incorporated Authorized Signatory